



New Project Proposal: SFF-TA-1050 Connectors for Accelerator Multipurpose Module (AMM)

Presented: 2026-08-28

Presenter: Zhineng Fan [Amphenol]

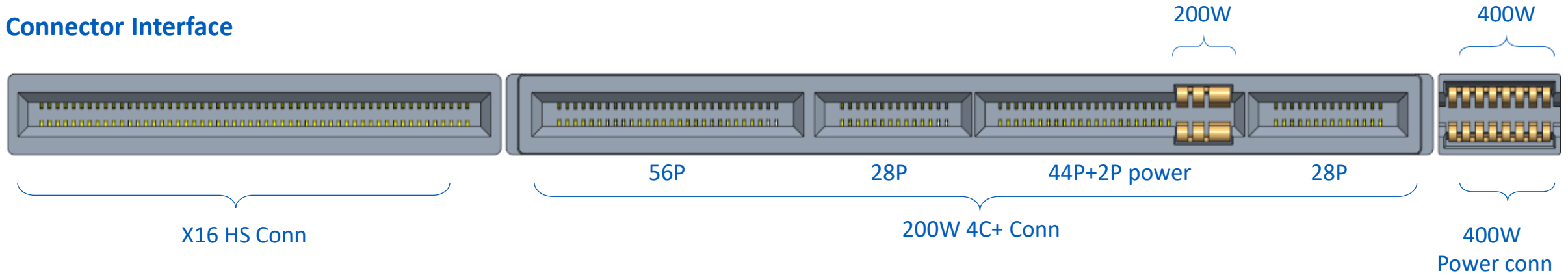
Supporters: Zhineng Fan [Amphenol] Thomas Ng
[Intel], Devang Soparkar [Microsoft]

New Project Proposal: SFF-TA-1050

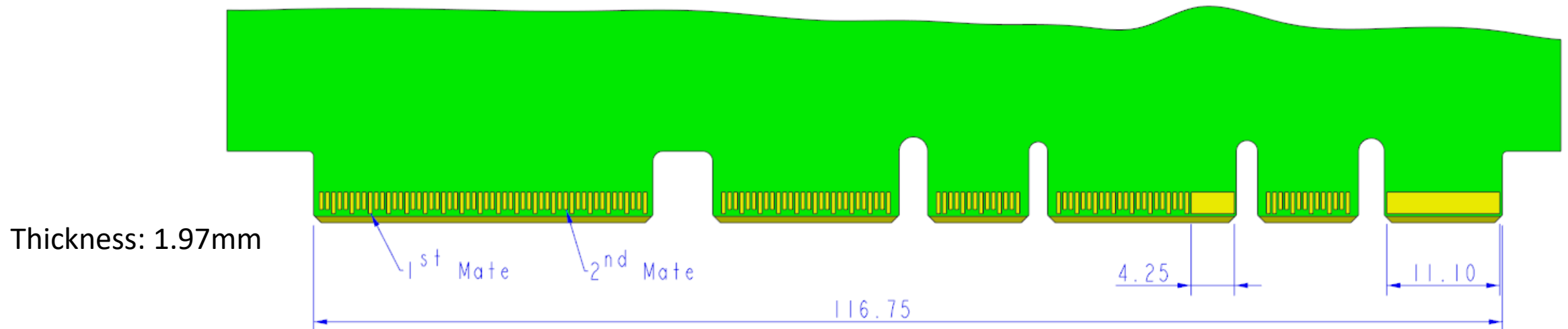
- The specification provides a connector solution that supports 1.97mm add-in-card module with high speed, sideband and power needs.
- Define connector-module interface and performance requirements
- The connector solution includes 3 individual connectors or a connector with ganged 3 modules :
 - 200W 4C+ connector/module
 - X16 high speed connector/module
 - 400W power connector/module
- Propose a mark to identify the connector type
- Editor(s): Zhineng Fan
- Supporters: Minimum 3 member companies required (can include editor's company)
 1. Amphenol
 2. Intel
 3. Microsoft

Mating Interface

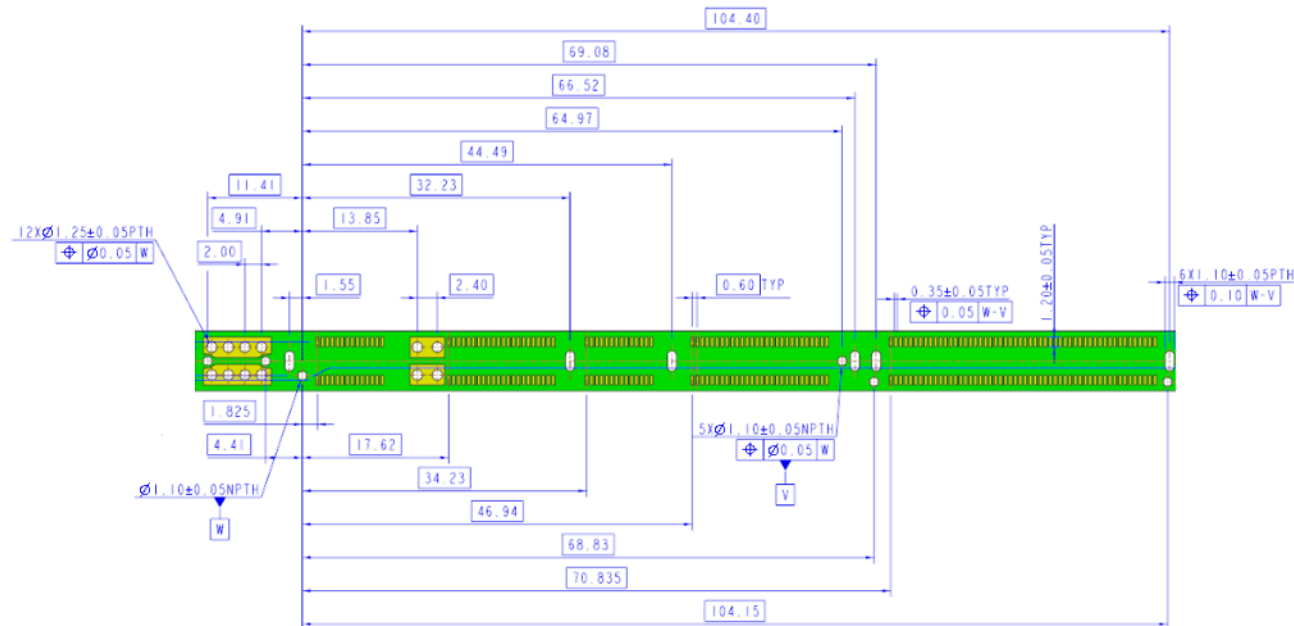
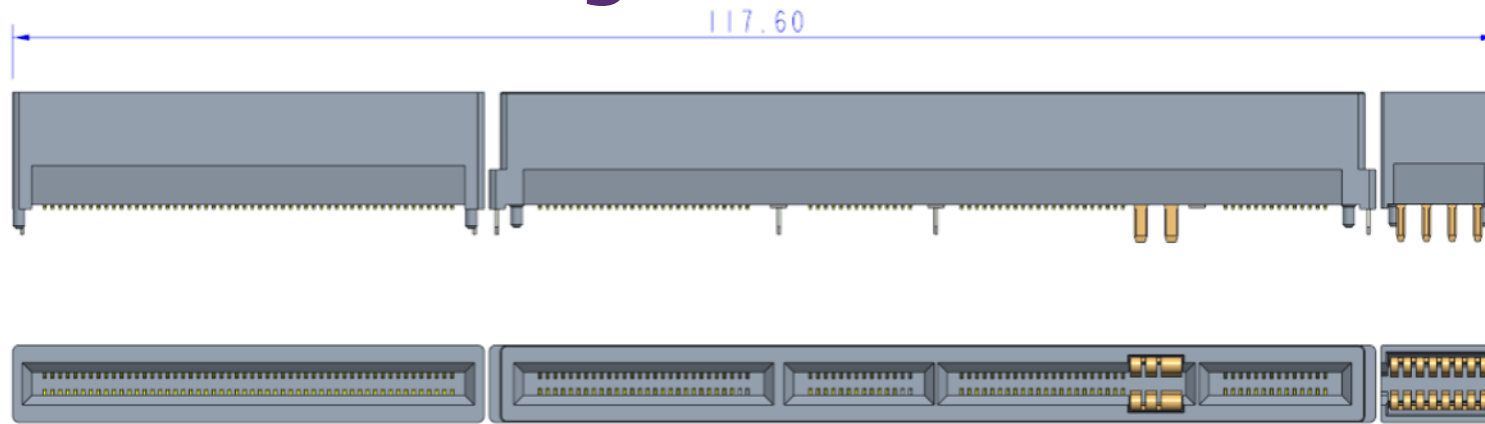
- Connector Interface



- AIC card interface



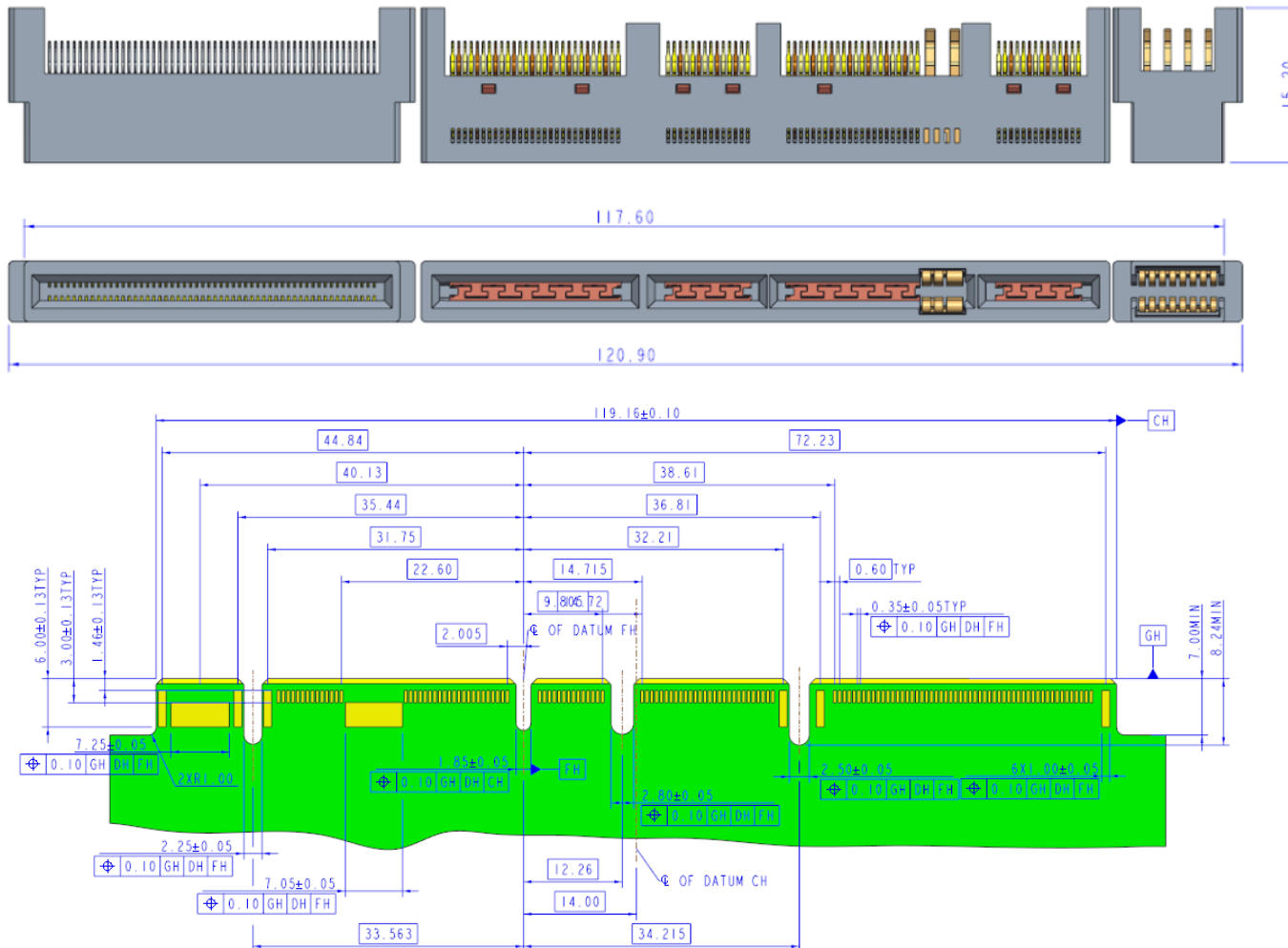
Vertical Connector Configuration



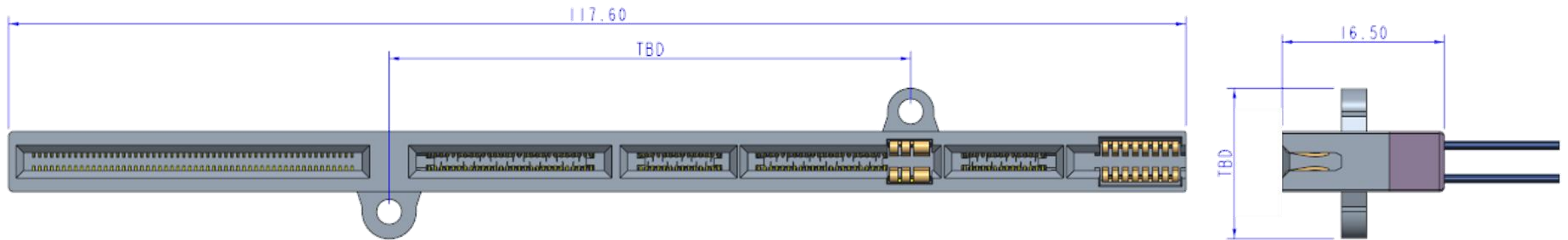
Right Angle Connector Configuration



Straddle Mount Connector Configuration



Panel Mount Connector Configuration



Type Identification

- 3 digits AIC thickness code follows the ground-link type that is the same definition as TA-1002)

High Speed Connectors

Tx-xxx

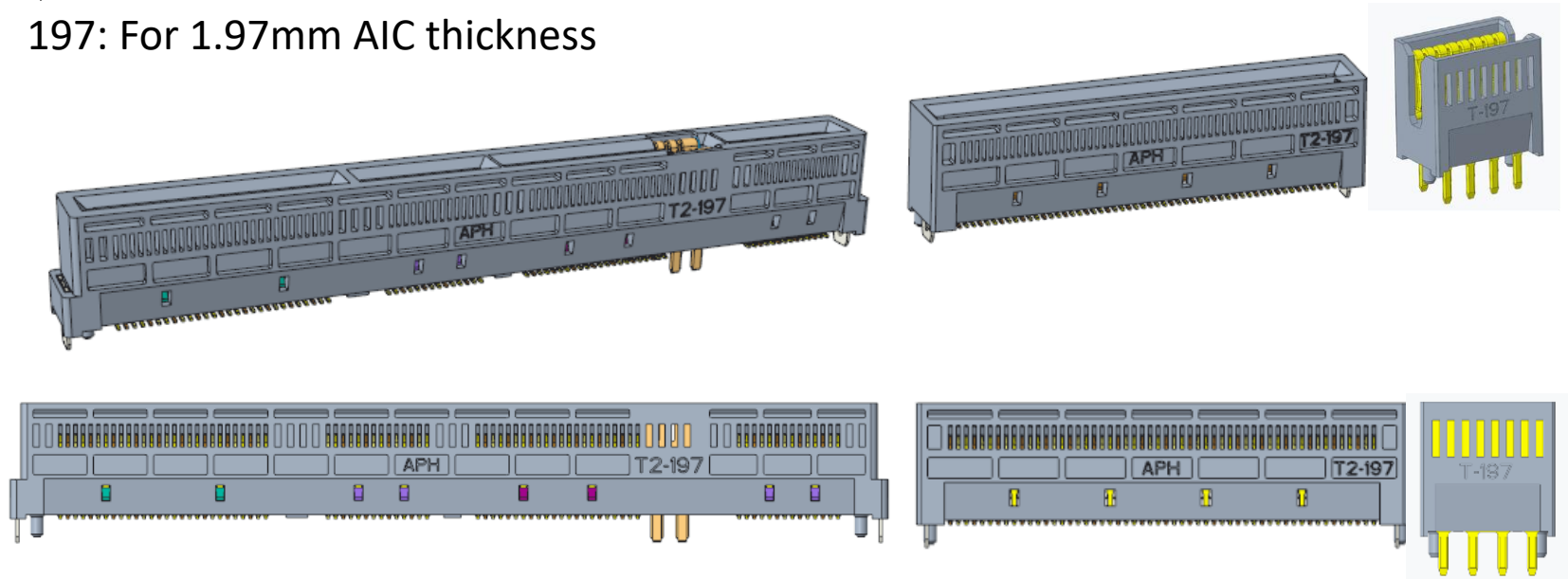
197: For 1.97mm AIC thickness

- 1: Ground not linked
- 2: Ground linked

Power Connector

T-xxx

197: For 1.97mm AIC thickness





Thank You

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